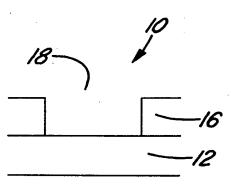
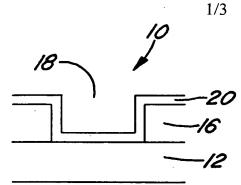
Inventor(s): Cheng-Wei Lee
Serial No.: To Be Assigned
Filed: Herewith
ethod For Forming Aluminum Bumps By Sputtering ...
Attorney Docket No.: 67,200-390



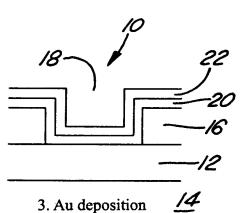
1. Pad open <u>/4</u> (PRIOR ART)

FIG. 1A



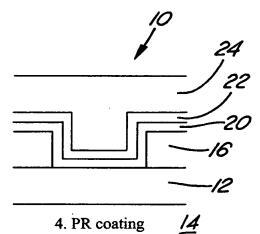
2. TiW deposition (PRIOR ART)

FIG. 1B



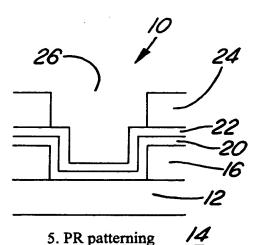
3. Au deposition (PRIOR ART)

FIG. 1C



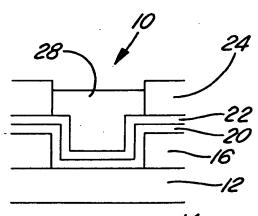
4. PR coating (PRIOR ART)

FIG. 1D



5. PR patterning (PRIOR ART)

FIG. 1E

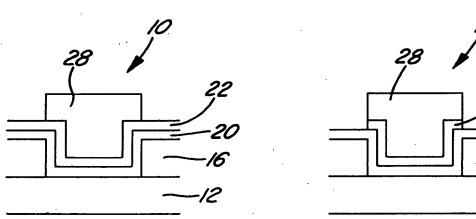


6. Gold plating (PRIOR ART)

FIG. 1F

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7. PR stripping (PRIOR ART)

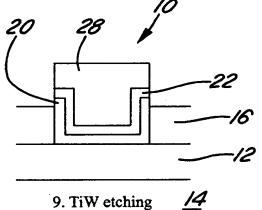
FIG. 1G

8. Gold etching (PRIOR ART)

2/3

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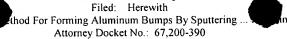
FIG. 1H



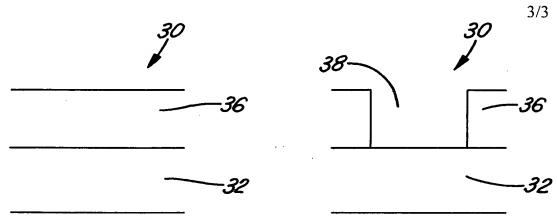
9. TiW etching (PRIOR ART)

FIG. 1I

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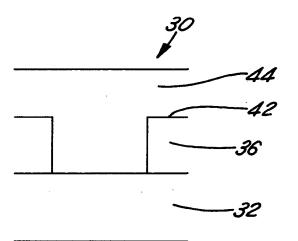


1. Thick passivation 34 deposition

2. Pad opening

FIG. 2A

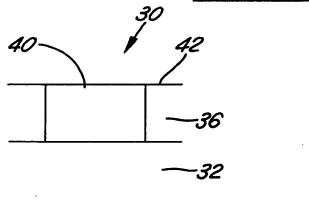
FIG. 2B



3. Al deposition

<u>34</u>

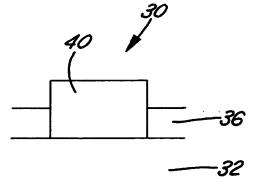
FIG. 20



4. Al polishing

<u>34</u>

FIG. 2D



5. Pass. dip back

<u>34</u>

FIG. 2E